

HYS72D32300GBR-[5/6/7]-B  
HYS72D643[00/20]GBR-[5/6/7]-B  
HYS72D128320GBR-[5/6/7]-B

184 - Pin Registered Double Data Rate SDRAM  
Modules

Reg DIMM  
DDR SDRAM

Memory Products



N e v e r   s t o p   t h i n k i n g .

**Edition 2004-04**

**Published by Infineon Technologies AG,  
St.-Martin-Strasse 53,  
81669 München, Germany**

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<b>Revision History:</b>	<b>Rev. 1.1</b>	<b>2004-04</b>
Previous Version:	Rev. 1.0	2003-12
Page	Subjects (major changes since last revision)	
21,22	Registerd and PLL current added	

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# 1 Overview

## 1.1 Features

- 184-Pin Registered 8-Byte Dual-In-Line DDR SDRAM Module for “1U” PC, Workstation and Server main memory applications
- One rank 32M × 72, 64M × 72 and two ranks 64M × 72, 128M × 72 organization
- JEDEC standard Double Data Rate Synchronous DRAMs (DDR SDRAM) with a single + 2.5 V (± 0.2 V) power supply and a single + 2.6 V (± 0.1 V) power supply for DDR400
- Built with 256-Mbit DDR-I SDRAMs in P-TFBGA-60-1 packages
- Programmable  $\overline{\text{CAS}}$  Latency, Burst Length, and Wrap Sequence (Sequential & Interleave)
- Auto Refresh (CBR) and Self Refresh
- All inputs and outputs SSTL\_2 compatible
- Re-drive for all input signals using register and PLL devices.
- Serial Presence Detect with E<sup>2</sup>PROM
- Low Profile Modules form factor:  
 128.95 mm × 28.58 mm × 4.00 mm  
 133.35 mm × 30.48 mm (1.2”) × 4.00 mm (6.80 mm with stacked components)
- JEDEC standard reference layout for one rank 256MB and 512MB, two ranks 512MB and 1GByte:  
 PC2700 Registered DIMM Raw Cards A,B,C,D
- Gold plated contacts

**Table 1 Performance**

Part Number Speed Code		-5	-6	-7	Unit	
Speed Grade	Component	DDR400B	DDR333B	DDR266A	—	
	Module	PC3200-3033	PC2700–2533	PC2100-2033	—	
max. Clock Frequency	@CL3	$f_{CK3}$	200	166	—	MHz
	@CL2.5	$f_{CK2.5}$	166	166	143	MHz
	@CL2	$f_{CK2}$	133	133	133	MHz

## 1.2 Description

The HYS72D[32/64/128]3[00/20]GBR are low profile versions of the standard Registered DIMM modules with less/equal 1.2” inch (30.48 mm) height for 1U Server Applications. The Low Profile DIMM versions are available as 32M × 72 (256MB), 64M × 72 (512MB) and 128M × 72 (1 GB).

The memory array is designed with Double Data Rate Synchronous DRAMs for ECC applications. All control and address signals are re-driven on the DIMM using register devices and a PLL for the clock distribution. This reduces capacitive loading to the system bus, but adds one cycle to the SDRAM timing. A variety of decoupling capacitors are mounted on the PC board. The DIMMs feature serial presence detect based on a serial E<sup>2</sup>PROM device using the 2-pin I<sup>2</sup>C protocol. The first 128 bytes are programmed with configuration data and the second 128 bytes are available to the customer.

**Table 2    Ordering Information**

Type	Compliance Code	Description	SDRAM Technology
<b>PC3200 (CL = 3, <math>t_{RP} = t_{RCD} = 3</math> at <math>t_{CK} = 5ns</math>)</b>			
HYS72D32300GBR-5-B	PC3200R-30330-A	one rank 256 MB Registered DIMM	256 Mbit (×8)
HYS72D64300GBR-5-B	PC3200R-30330-C	one rank 512 MB Registered DIMM	256 Mbit (×4)
HYS72D64320GBR-5-B	PC3200R-30330-B	two ranks 512 MB Registered DIMM	256 Mbit (×8)
HYS72D128320GBR-5-B	PC3200R-30331-D	two ranks 1 GB Registered DIMM	256 Mbit (×4)
<b>PC2700 (CL = 2.5, <math>t_{RP} = t_{RCD} = 3</math> at <math>t_{CK} = 6ns</math>)</b>			
HYS72D32300GBR-6-B	PC2700R-25330-A	one rank 256 MB Registered DIMM	256 Mbit (×8)
HYS72D64300GBR-6-B	PC2700R-25330-C	one rank 512 MB Registered DIMM	256 Mbit (×4)
HYS72D64320GBR-6-B	PC2700R-25330-B	two ranks 512 MB Registered DIMM	256 Mbit (×8)
HYS72D128320GBR-6-B	PC2700R-25330-D	two ranks 1 GB Registered DIMM	256 Mbit (×4)
<b>PC2100 (CL = 2, <math>t_{RP} = t_{RCD} = 3</math> at <math>t_{CK} = 7.5ns</math>)</b>			
HYS72D32300GBR-7-B	PC2100R-20330-A	one rank 256 MB Registered DIMM	256 Mbit (×8)
HYS72D64300GBR-7-B	PC2100R-20330-C	one rank 512 MB Registered DIMM	256 Mbit (×4)
HYS72D64320GBR-7-B	PC2100R-20330-B	two ranks 512 MB Registered DIMM	256 Mbit (×8)
HYS72D128320GBR-7-B	PC2100R-20330-D	two ranks 1 GB Registered DIMM	256 Mbit (×4)

*Note: All "product type" end with a place code designating the silicon-die revision. Reference information available on request. Example: HYS72D64300GR-5-B, indicating rev. C dies are used for SDRAM components. The "compliance code" is printed on the module labels describing the speed sort (for example "PC2700"), the latencies and SPD code definition (for example "20330" means CAS latency of 2.0 clocks,  $RCD^{1)}$  latency of 3 clocks, Row Precharge latency of 3 clocks, and JEDEC SPD code definition version 0), and the Row Card used for this module.*

1) RCD: Row-Column-Delay

## 2 Pin Configuration

The pin configuration of the Registered DDR SDRAM DIMM is listed by function in **Table 3** (184 pins). The abbreviations used in columns Pin and Buffer Type are explained in **Table 4** and **Table 5** respectively. The pin numbering is depicted in **Figure 1**.

**Table 3 Pin Configuration of RDIMM**

Pin#	Name	Pin Type	Buffer Type	Function
<b>Clock Signals</b>				
137	CK0	I	SSTL	<b>Clock Signal</b>
138	$\overline{\text{CK0}}$	I	SSTL	<b>Complement Clock</b>
21	CKE0	I	SSTL	<b>Clock Enable Rank 0</b>
111	CKE1	I	SSTL	<b>Clock Enable Rank 1</b> <i>Note: 2-rank module</i>
	NC	NC	SSTL	<i>Note: 1-rank module</i>
<b>Control Signals</b>				
157	$\overline{\text{S0}}$	I	SSTL	<b>Chip Select of Rank 0</b>
158	$\overline{\text{S1}}$	I	SSTL	<b>Chip Select of Rank 1</b> <i>Note: 2-ranks module</i>
	NC	NC	–	<i>Note: 1-rank module</i>
154	$\overline{\text{RAS}}$	I	SSTL	<b>Row Address Strobe</b>
65	$\overline{\text{CAS}}$	I	SSTL	<b>Column Address Strobe</b>
63	$\overline{\text{WE}}$	I	SSTL	<b>Write Enable</b>
10	$\overline{\text{RESET}}$	I	LV-CMOS	<b>Register Reset</b> Forces registered inputs low <i>Note: For detailed description of the Power Up and Power Management see the Application Note at the end of data sheet</i>
<b>Address Signals</b>				
59	BA0	I	SSTL	<b>Bank Address Bus 1:0</b>
52	BA1	I	SSTL	
48	A0	I	SSTL	<b>Address Bus 11:0</b>
43	A1	I	SSTL	
41	A2	I	SSTL	
130	A3	I	SSTL	
37	A4	I	SSTL	
32	A5	I	SSTL	

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function
125	A6	I	SSTL	<b>Address Bus 11:0</b>
29	A7	I	SSTL	
122	A8	I	SSTL	
27	A9	I	SSTL	
141	A10	I	SSTL	
	AP	I	SSTL	
118	A11	I	SSTL	
115	A12	I	SSTL	<b>Address Signal 12</b> <i>Note: Module based on 256 Mbit or larger dies</i>
	NC	NC	–	<i>Note: 128 Mbit based module</i>
167	A13	I	SSTL	<b>Address Signal 13</b> <i>Note: 1 Gbit based module</i>
	NC	NC	–	<i>Note: Module based on 512 Mbit or smaller dies</i>



**Pin Configuration**

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function
<b>Data Signals</b>				
2	DQ0	I/O	SSTL	<b>Data Bus 63:0</b>
4	DQ1	I/O	SSTL	
6	DQ2	I/O	SSTL	
8	DQ3	I/O	SSTL	
94	DQ4	I/O	SSTL	
95	DQ5	I/O	SSTL	
98	DQ6	I/O	SSTL	
99	DQ7	I/O	SSTL	
12	DQ8	I/O	SSTL	
13	DQ9	I/O	SSTL	
19	DQ10	I/O	SSTL	
20	DQ11	I/O	SSTL	
105	DQ12	I/O	SSTL	
106	DQ13	I/O	SSTL	
109	DQ14	I/O	SSTL	
110	DQ15	I/O	SSTL	
23	DQ16	I/O	SSTL	
24	DQ17	I/O	SSTL	
28	DQ18	I/O	SSTL	
31	DQ19	I/O	SSTL	
114	DQ20	I/O	SSTL	
117	DQ21	I/O	SSTL	
121	DQ22	I/O	SSTL	
123	DQ23	I/O	SSTL	
33	DQ24	I/O	SSTL	
35	DQ25	I/O	SSTL	
39	DQ26	I/O	SSTL	
40	DQ27	I/O	SSTL	
126	DQ28	I/O	SSTL	
127	DQ29	I/O	SSTL	
131	DQ30	I/O	SSTL	
133	DQ31	I/O	SSTL	
53	DQ32	I/O	SSTL	
55	DQ33	I/O	SSTL	
57	DQ34	I/O	SSTL	
60	DQ35	I/O	SSTL	
146	DQ36	I/O	SSTL	
147	DQ37	I/O	SSTL	

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function	
150	DQ38	I/O	SSTL	<b>Data Bus 63:0</b>	
151	DQ39	I/O	SSTL		
61	DQ40	I/O	SSTL		
64	DQ41	I/O	SSTL		
68	DQ42	I/O	SSTL		
69	DQ43	I/O	SSTL		
153	DQ44	I/O	SSTL		
155	DQ45	I/O	SSTL		
161	DQ46	I/O	SSTL		
162	DQ47	I/O	SSTL		
72	DQ48	I/O	SSTL		
73	DQ49	I/O	SSTL		
79	DQ50	I/O	SSTL		
80	DQ51	I/O	SSTL		
165	DQ52	I/O	SSTL		
166	DQ53	I/O	SSTL		
170	DQ54	I/O	SSTL		
171	DQ55	I/O	SSTL		
83	DQ56	I/O	SSTL		
84	DQ57	I/O	SSTL		
87	DQ58	I/O	SSTL		
88	DQ59	I/O	SSTL		
174	DQ60	I/O	SSTL		
175	DQ61	I/O	SSTL		
178	DQ62	I/O	SSTL		
179	DQ63	I/O	SSTL		
44	CB0	I/O	SSTL		<b>Check Bits 7:0</b>
45	CB1	I/O	SSTL		
49	CB2	I/O	SSTL		
51	CB3	I/O	SSTL		
134	CB4	I/O	SSTL		
135	CB5	I/O	SSTL		
142	CB6	I/O	SSTL		
144	CB7	I/O	SSTL		
5	DQS0	I/O	SSTL		<b>Data Strobes 8:0</b> <i>Note: See block diagram for corresponding DQ signals</i>
14	DQS1	I/O	SSTL		
25	DQS2	I/O	SSTL		
36	DQS3	I/O	SSTL		
56	DQS4	I/O	SSTL		
67	DQS5	I/O	SSTL		

**Pin Configuration**

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function
78	DQS6	I/O	SSTL	<b>Data Strobes 8:0</b>
86	DQS7	I/O	SSTL	
47	DQS8	I/O	SSTL	
97	DM0	I	SSTL	<b>Data Mask 0</b> <i>Note: x8 based module</i>
	DQS9	I/O	SSTL	<b>Data Strobe 9</b> <i>Note: x4 based module</i>
107	DM1	I	SSTL	<b>Data Mask 1</b> <i>Note: x8 based module</i>
	DQS10	I/O	SSTL	<b>Data Strobe 10</b> <i>Note: x4 based module</i>
119	DM2	I	SSTL	<b>Data Mask 2</b> <i>Note: x8 based module</i>
	DQS11	I/O	SSTL	<b>Data Strobe 11</b> <i>Note: x4 based module</i>
129	DM3	I	SSTL	<b>Data Mask 3</b> <i>Note: x8 based module</i>
	DQS12	I/O	SSTL	<b>Data Strobe 12</b> <i>Note: x4 based module</i>
149	DM4	I	SSTL	<b>Data Mask 4</b> <i>Note: x8 based module</i>
	DQS13	I/O	SSTL	<b>Data Strobe 13</b> <i>Note: x4 based module</i>
159	DM5	I	SSTL	<b>Data Mask 5</b> <i>Note: x8 based module</i>
	DQS14	I/O	SSTL	<b>Data Strobe 14</b> <i>Note: x4 based module</i>
169	DM6	I	SSTL	<b>Data Mask 6</b> <i>Note: x8 based module</i>
	DQS15	I/O	SSTL	<b>Data Strobe 15</b> <i>Note: x4 based module</i>
177	DM7	I	SSTL	<b>Data Mask 7</b> <i>Note: x8 based module</i>
	DQS16	I/O	SSTL	<b>Data Strobe 16</b> <i>Note: x4 based module</i>
140	DM8	I	SSTL	<b>Data Mask 8</b> <i>Note: x8 based module</i>
	DQS17	I/O	SSTL	<b>Data Strobe 17</b> <i>Note: x4 based module</i>

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function
<b>EEPROM</b>				
92	SCL	I	CMOS	<b>Serial Bus Clock</b>
91	SDA	I/O	OD	<b>Serial Bus Data</b>
181	SA0	I	CMOS	<b>Slave Address Select Bus 2:0</b>
182	SA1	I	CMOS	
183	SA2	I	CMOS	
<b>Power Supplies</b>				
1	$V_{REF}$	AI	–	<b>I/O Reference Voltage</b>
184	$V_{DDSPD}$	PWR	–	<b>EEPROM Power Supply</b>
15, 22, 30, 54, 62, 77, 96, 104, 112, 128, 136, 143, 156, 164, 172, 180	$V_{DDQ}$	PWR	–	<b>I/O Driver Power Supply</b>
7, 38, 46, 70, 85, 108, 120, 148, 168	$V_{DD}$	PWR	–	<b>Power Supply</b>

**Table 3 Pin Configuration of RDIMM (cont'd)**

Pin#	Name	Pin Type	Buffer Type	Function
3, 11, 18, 26, 34, 42, 50, 58, 66, 74, 81, 89, 93, 100, 116, 124, 132, 139, 145, 152, 160, 176	$V_{SS}$	GND	–	<b>Ground Plane</b>

**Other Pins**

82	$V_{DDID}$	O	OD	<b><math>V_{DD}</math> Identification</b> <i>Note: Pin in tristate, indicating <math>V_{DD}</math> and <math>V_{DDQ}</math> nets connected on PCB</i>
9, 16, 17, 71, 75, 76, 90, 101, 102, 103, 113, 163, 173	NC	NC	–	<b>Not connected</b> Pins not connected on Infineon RDIMM's

**Table 4 Abbreviations for Pin Type**

Abbreviation	Description
I	Standard input-only pin. Digital levels.
O	Output. Digital levels.
I/O	I/O is a bidirectional input/output signal.
AI	Input. Analog levels.
PWR	Power
GND	Ground
NU	Not Usable (JEDEC Standard)
NC	Not Connected (JEDEC Standard)

**Table 5 Abbreviations for Buffer Type**

Abbreviation	Description
SSTL	Serial Stub Terminated Logic (SSTL2)
LV-CMOS	Low Voltage CMOS
CMOS	CMOS Levels
OD	Open Drain. The corresponding pin has 2 operational states, active low and tristate, and allows multiple devices to share as a wire-OR.

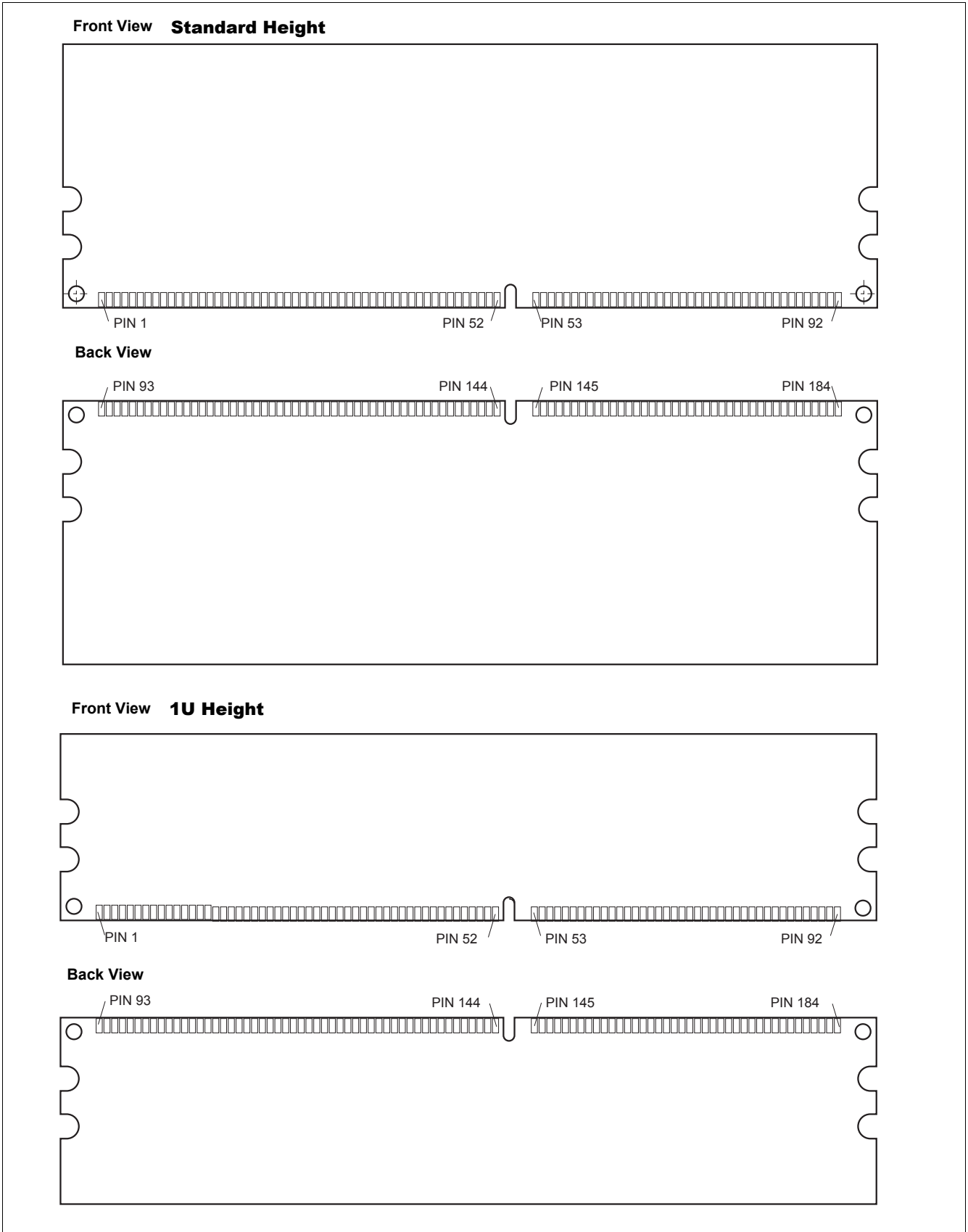


Figure 1 PCB with Pin Connector

**Table 6 Address Format**

Density	Organization	Memory Ranks	SDRAMs	# of SDRAMs	# of row/bank/columns bits	Refresh	Period	Interval
256 MB	32M x 72	1	32M x8	9	13 / 2 / 10	8K	64 ms	7.8 μs
512 MB	64M x 72	1	64M x4	18	13 / 2 / 11	8K	64 ms	7.8 μs
512 MB	64M x 72	2	32M x8	18	13 / 2 / 10	8K	64 ms	7.8 μs
1 GB	128M x 72	2	64M x4	36	13 / 2 / 11	8K	64 ms	7.8 μs

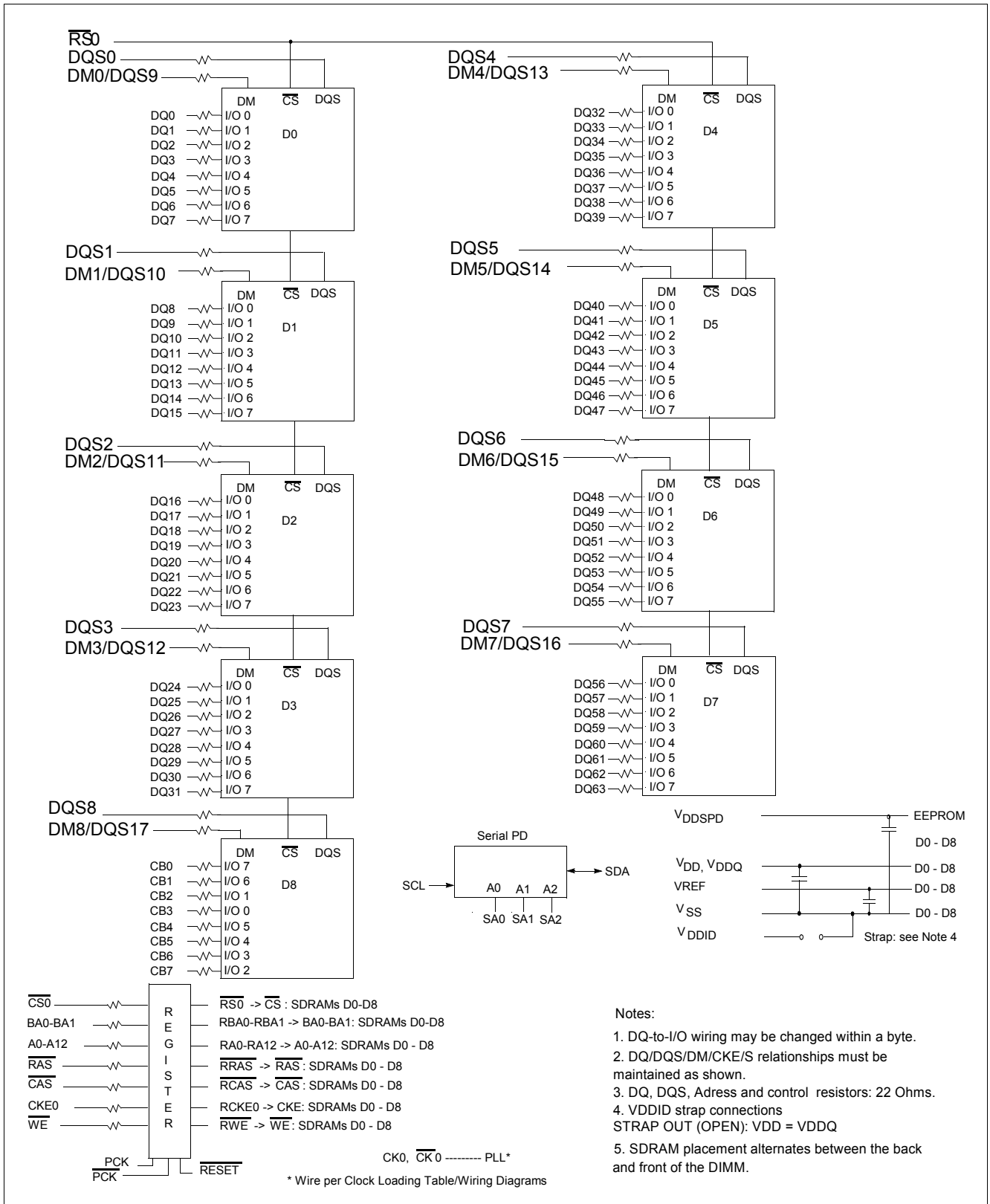
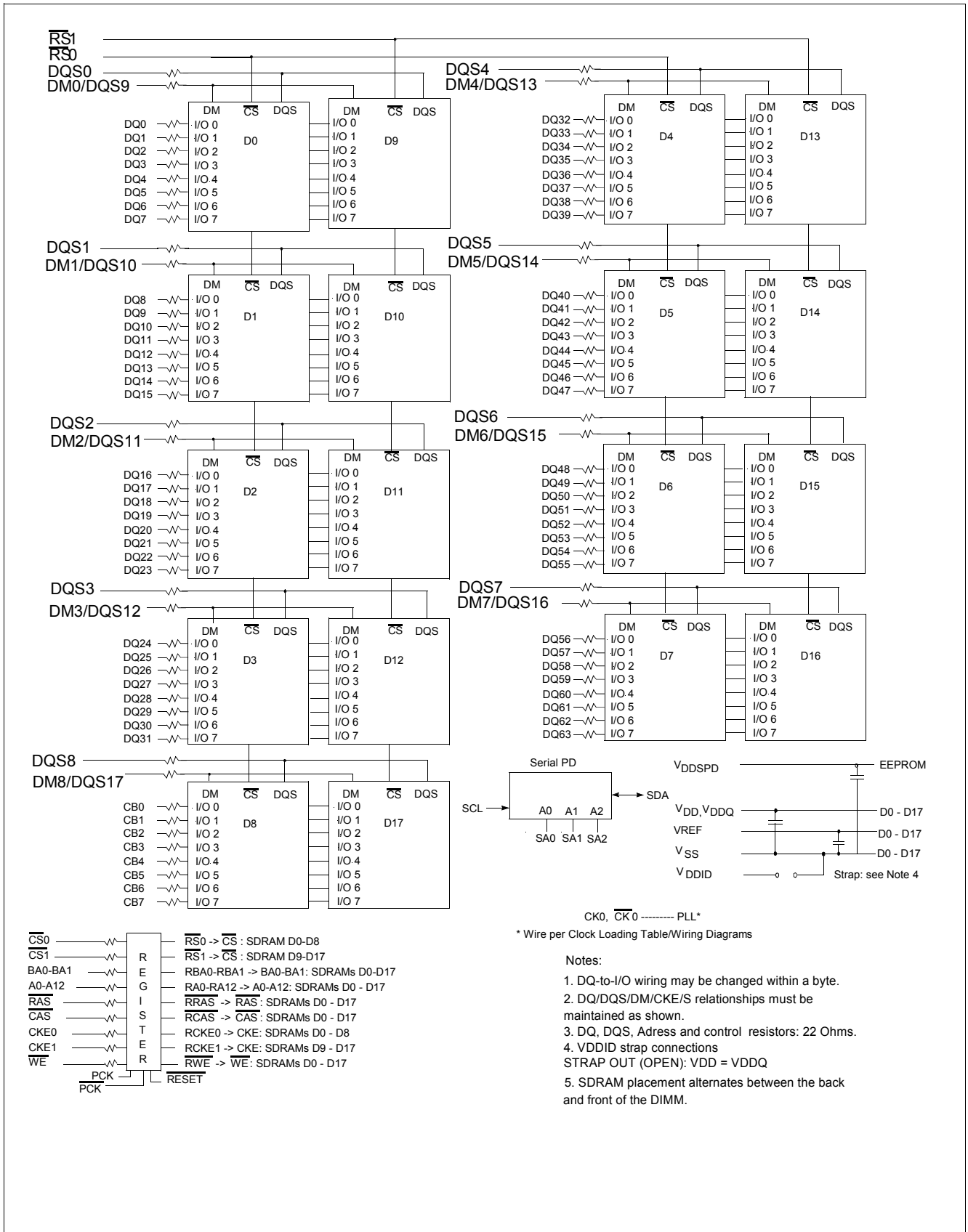


Figure 2 Block Diagram: One Rank 32M x 72 DDR SDRAM DIMM Module (32Mx8 components) HYS72D32300GBR on Raw Card A



**Figure 3 Block Diagram: Two Ranks 64M x 72 DDR-I SDRAM DIMM Module (32Mx8 components) HYS 72D64320GBR on Raw Card B**

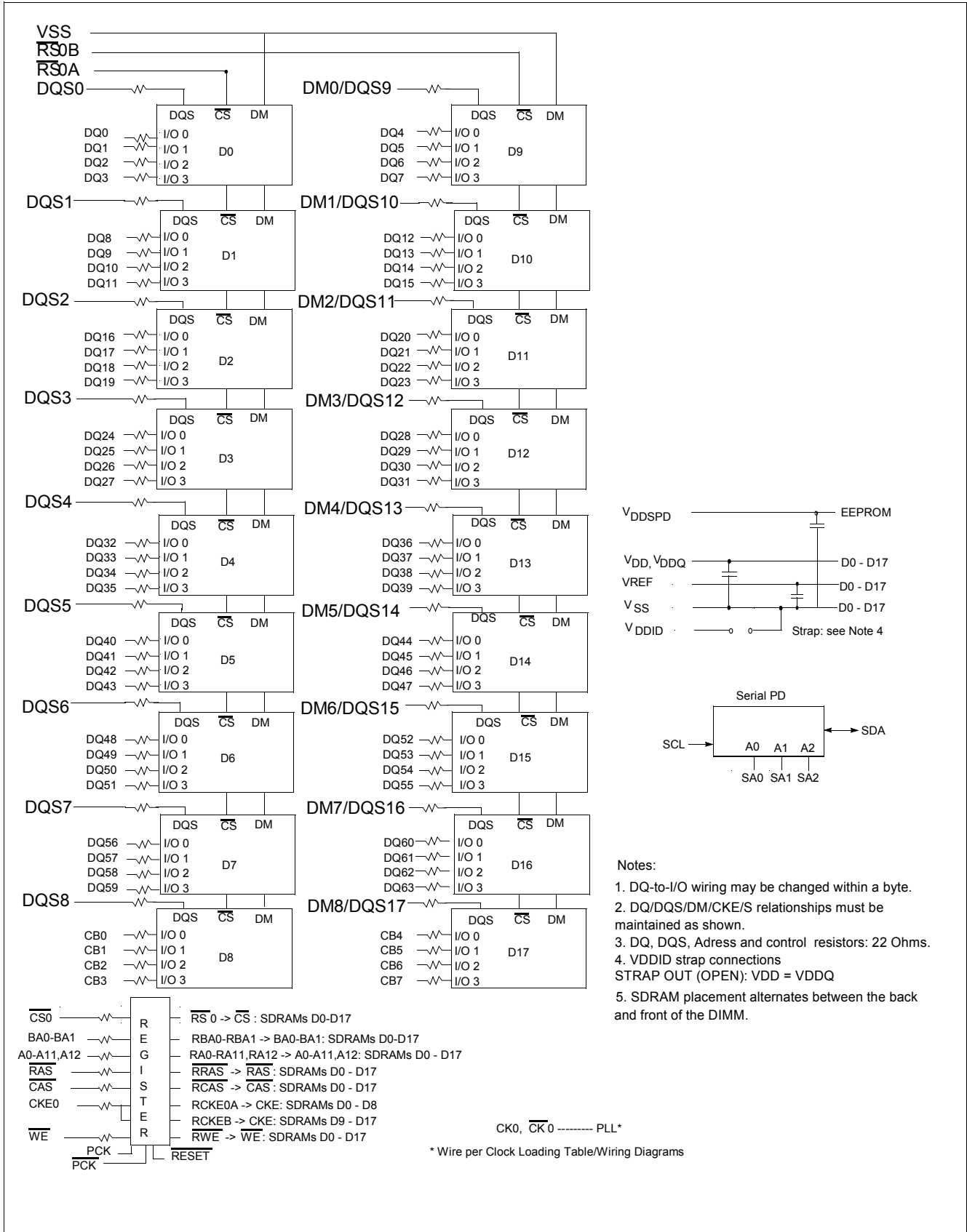
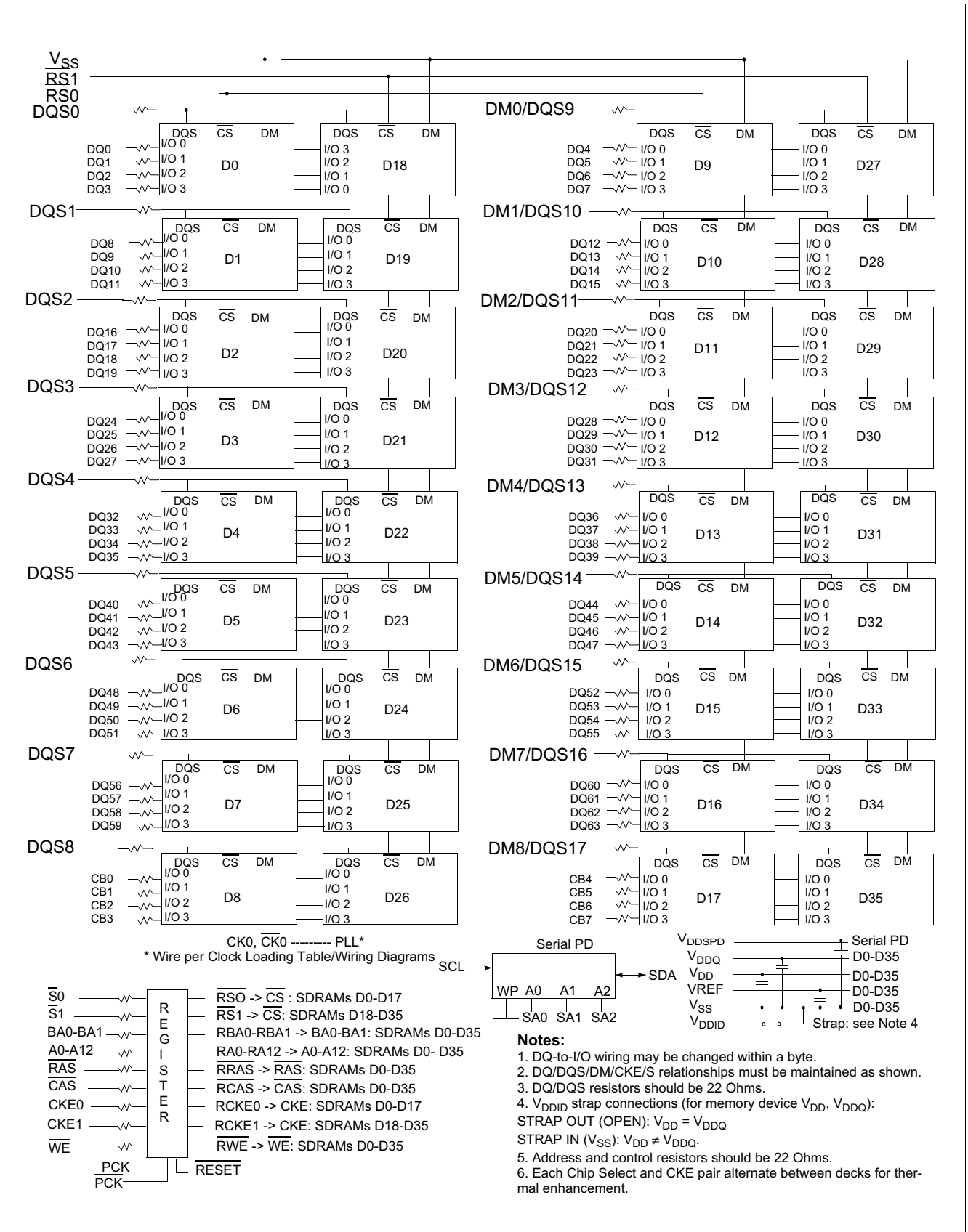


Figure 4 Block Diagram: One Rank 64M x 72 DDR-I SDRAM DIMM Modules (64Mx4 components) HYS72D64300GBR on Raw Card C





**Figure 5 Block Diagram: Two Ranks 128M x 72 DDR SDRAM DIMM Modules (64M x 4 components) HYS72D128320GBR on Raw Card D**

### 3 Electrical Characteristics

#### 3.1 Operating Conditions

**Table 7 Absolute Maximum Ratings**

Parameter	Symbol	Values			Unit	Note/ Test Condition
		min.	typ.	max.		
Voltage on I/O pins relative to $V_{SS}$	$V_{IN}, V_{OUT}$	-0.5	–	$V_{DDQ} + 0.5$	V	–
Voltage on inputs relative to $V_{SS}$	$V_{IN}$	-0.5	–	+3.6	V	–
Voltage on $V_{DD}$ supply relative to $V_{SS}$	$V_{DD}$	-0.5	–	+3.6	V	–
Voltage on $V_{DDQ}$ supply relative to $V_{SS}$	$V_{DDQ}$	-0.5	–	+3.6	V	–
Operating temperature (ambient)	$T_A$	0	–	+70	°C	–
Storage temperature (plastic)	$T_{STG}$	-55	–	+150	°C	–
Power dissipation (per SDRAM component)	$P_D$	–	2.0	–	W	–
Short circuit output current	$I_{OUT}$	–	50	–	mA	–

**Attention: Permanent damage to the device may occur if “Absolute Maximum Ratings” are exceeded. This is a stress rating only, and functional operation should be restricted to recommended operation conditions. Exposure to absolute maximum rating conditions for extended periods of time may affect device reliability and exceeding only one of the values may cause irreversible damage to the integrated circuit.**

**Table 8 Electrical Characteristics and DC Operating Conditions**

Parameter	Symbol	Values			Unit	Note/Test Condition <sup>1)</sup>
		Min.	Typ.	Max.		
Device Supply Voltage	$V_{DD}$	2.3	2.5	2.7	V	$f_{CK} \leq 166$ MHz
Device Supply Voltage	$V_{DD}$	2.5	2.6	2.7	V	$f_{CK} > 166$ MHz <sup>2)</sup>
Output Supply Voltage	$V_{DDQ}$	2.3	2.5	2.7	V	$f_{CK} \leq 166$ MHz <sup>3)</sup>
Output Supply Voltage	$V_{DDQ}$	2.5	2.6	2.7	V	$f_{CK} > 166$ MHz <sup>2)3)</sup>
EEPROM supply voltage	$V_{DDSPD}$	2.3	2.5	3.6	V	–
Supply Voltage, I/O Supply Voltage	$V_{SS}, V_{SSQ}$	0		0	V	–
Input Reference Voltage	$V_{REF}$	$0.49 \times V_{DDQ}$	$0.5 \times V_{DDQ}$	$0.51 \times V_{DDQ}$	V	<sup>4)</sup>
I/O Termination Voltage (System)	$V_{TT}$	$V_{REF} - 0.04$		$V_{REF} + 0.04$	V	<sup>5)</sup>
Input High (Logic1) Voltage	$V_{IH(DC)}$	$V_{REF} + 0.15$		$V_{DDQ} + 0.3$	V	<sup>8)</sup>
Input Low (Logic0) Voltage	$V_{IL(DC)}$	-0.3		$V_{REF} - 0.15$	V	<sup>8)</sup>
Input Voltage Level, CK and $\overline{CK}$ Inputs	$V_{IN(DC)}$	-0.3		$V_{DDQ} + 0.3$	V	<sup>8)</sup>
Input Differential Voltage, CK and $\overline{CK}$ Inputs	$V_{ID(DC)}$	0.36		$V_{DDQ} + 0.6$	V	<sup>8)6)</sup>
VI-Matching Pull-up Current to Pull-down Current	$V_{I_{Ratio}}$	0.71		1.4	–	<sup>7)</sup>

**Table 8 Electrical Characteristics and DC Operating Conditions (cont'd)**

Parameter	Symbol	Values			Unit	Note/Test Condition <sup>1)</sup>
		Min.	Typ.	Max.		
Input Leakage Current	$I_I$	-2		2	$\mu\text{A}$	Any input $0\text{ V} \leq V_{IN} \leq V_{DD}$ ; All other pins not under test = 0 V <sup>8)9)</sup>
Output Leakage Current	$I_{OZ}$	-5		5	$\mu\text{A}$	DQs are disabled; $0\text{ V} \leq V_{OUT} \leq V_{DDQ}$
Output High Current, Normal Strength Driver	$I_{OH}$	—		-16.2	mA	$V_{OUT} = 1.95\text{ V}$
Output Low Current, Normal Strength Driver	$I_{OL}$	16.2		—	mA	$V_{OUT} = 0.35\text{ V}$

- 1)  $0\text{ }^\circ\text{C} \leq T_A \leq 70\text{ }^\circ\text{C}$
- 2) DDR400 conditions apply for all clock frequencies above 166 MHz
- 3) Under all conditions,  $V_{DDQ}$  must be less than or equal to  $V_{DD}$ .
- 4) Peak to peak AC noise on  $V_{REF}$  may not exceed  $\pm 2\% V_{REF(DC)}$ .  $V_{REF}$  is also expected to track noise variations in  $V_{DDQ}$ .
- 5)  $V_{TT}$  is not applied directly to the device.  $V_{TT}$  is a system supply for signal termination resistors, is expected to be set equal to  $V_{REF}$ , and must track variations in the DC level of  $V_{REF}$ .
- 6)  $V_{ID}$  is the magnitude of the difference between the input level on CK and the input level on  $\overline{CK}$ .
- 7) The ratio of the pull-up current to the pull-down current is specified for the same temperature and voltage, over the entire temperature and voltage range, for device drain to source voltage from 0.25 to 1.0 V. For a given output, it represents the maximum difference between pull-up and pull-down drivers due to process variation.
- 8) Inputs are not recognized as valid until  $V_{REF}$  stabilizes.
- 9) Values are shown per DDR SDRAM component

**Table 9**  $I_{DD}$  Specifications

Product Type & Organisation	HYS72D32300GBR-5-B		HYS72D64300GBR-5-B		HYS72D64320GBR-5-B		HYS72D128320GBR-5-B		Unit	Note/ Test Conditions <sup>5)</sup>
	256 MB ×72 1 Rank -5		512 MB ×72 1 Rank -5		512 MB ×72 2 Ranks -5		1 GByte ×72 2 Ranks -5			
	typ.	max.	typ.	max.	typ.	max.	typ.	max.		
$I_{DD0}$	1690	1960	2500	3040	2284	2599	3688	4318	mA	1)4)
$I_{DD1}$	1825	2005	2770	3130	2419	2644	3958	4408	mA	1)3)4)
$I_{DD2P}$	698	725	752	806	752	806	860	968	mA	2)4)
$I_{DD2F}$	1076	1139	1508	1634	1508	1634	2372	2624	mA	2)4)
$I_{DD2Q}$	878	932	1112	1220	1112	1220	1580	1796	mA	2)4)
$I_{DD3P}$	815	869	986	1094	986	1094	1328	1544	mA	2)4)
$I_{DD3N}$	1238	1319	1832	1994	1832	1994	3020	3344	mA	2)4)
$I_{DD4R}$	2005	2185	3130	3490	2599	2824	4318	4768	mA	1)3)4)
$I_{DD4W}$	2005	2194	3130	3508	2599	2833	4318	4786	mA	1)4)
$I_{DD5}$	2320	2635	3760	4390	2914	3274	4948	5668	mA	1)4)
$I_{DD6}$	656.6	671	669.2	698	669.2	698	694.4	752	mA	2)4)
$I_{DD7}$	3040	3310	5200	5740	3634	3949	6388	7018	mA	1)3)4)

- 1) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $n * I_{DD} \times [\text{component}] + n * I_{DD3N} [\text{component}]$  for two bank modules (n: number of components per module bank)
- 2) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $2 * n * I_{DD} \times [\text{component}]$  for single two bank modules (n: number of components per module bank)
- 3) DQ I/O ( $I_{DDQ}$ ) currents are not included into calculations: module  $I_{DD}$  values will be measured differently depending on load conditions
- 4) Module  $I_{DD}$  is calculated on the basis of component  $I_{DD}$  and includes Register and PLL
- 5) Test condition for maximum values:  $V_{DD} = 2.7 \text{ V}$ ,  $T_A = 10 \text{ °C}$

**Table 10**  $I_{DD}$  Specifications

Product Type & Organisation	HYS72D32300GBR-6-B		HYS72D64300GBR-6-B		HYS72D64320GBR-6-B		HYS72D128320GBR-6-B		Unit	Note/ Test Conditions <sup>5)</sup>
	256 MB ×72 1 Rank -6	512 MB ×72 1Ranks -6	512 MB ×72 2 Ranks -6	512 MB ×72 2 Ranks -6	1 GB ×72 2 Ranks -6	1 GB ×72 2 Ranks -6	1 GB ×72 2 Ranks -6	1 GB ×72 2 Ranks -6		
	typ.	max.	typ.	max.	typ.	max.	typ.	max.		
$I_{DD0}$	1495	1720	2260	2710	2035	2305	3340	3880	mA	1)4)
$I_{DD1}$	1630	1810	2530	2890	2170	2395	3610	4060	mA	1)3)4)
$I_{DD2P}$	484	511	538	592	538	592	646	754	mA	2)4)
$I_{DD2F}$	835	925	1240	1420	1240	1420	2050	2410	mA	2)4)
$I_{DD2Q}$	652	682	875	934	875	934	1319	1438	mA	2)4)
$I_{DD3P}$	592	619	754	808	754	808	1078	1186	mA	2)4)
$I_{DD3N}$	970	1015	1510	1600	1510	1600	2590	2770	mA	2)4)
$I_{DD4R}$	1720	1990	2710	3250	2260	2575	3790	4420	mA	1)3)4)
$I_{DD4W}$	1855	2035	2980	3340	2395	2620	4060	4510	mA	1)4)
$I_{DD5}$	2022	2440	3313	4150	2562	3025	4393	5320	mA	1)4)
$I_{DD6}$	444	453	457	475	457	475	484	520	mA	2)4)
$I_{DD7}$	2600	3160	4470	5590	3140	3745	5550	6760	mA	1)3)4)

- 1) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $n * I_{DD} \times [\text{component}] + n * I_{DD3N} [\text{component}]$  for two bank modules (n: number of components per module bank)
- 2) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $2 * n * I_{DD} \times [\text{component}]$  for single two bank modules (n: number of components per module bank)
- 3) DQ I/O ( $I_{DDQ}$ ) currents are not included into calculations: module  $I_{DD}$  values will be measured differently depending on load conditions
- 4) Module  $I_{DD}$  is calculated on the basis of component  $I_{DD}$  and includes Register and PLL
- 5) Test condition for maximum values:  $V_{DD} = 2.7 \text{ V}$ ,  $T_A = 10 \text{ °C}$

**Table 11**  $I_{DD}$  Specifications

Product Type & Organisation	HYS72D32300GBR-7-B		HYS72D64300GBR-7-B		HYS72D64320GBR-7-B		HYS72D128320GBR-7-B		Unit	Note/ Test Conditions <sup>5)</sup>
	256 MB ×72 1 Rank -7	512 MB ×72 1 Rank -7	512 MB ×72 2 Ranks -7	1 GB ×72 2 Ranks -7	typ.	max.	typ.	max.		
$I_{DD0}$	1263	1488	1938	2388	1713	1983	2838	3378	mA	1)4)
$I_{DD1}$	1398	1578	2208	2568	1848	2073	3108	3558	mA	1)3)4)
$I_{DD2P}$	426	448	475	520	475	520	574	664	mA	2)4)
$I_{DD2F}$	691	736	1006	1096	1006	1096	1636	1816	mA	2)4)
$I_{DD2Q}$	556	601	736	826	736	826	1096	1276	mA	2)4)
$I_{DD3P}$	511	538	646	700	646	700	916	1024	mA	2)4)
$I_{DD3N}$	826	871	1276	1366	1276	1366	2176	2356	mA	2)4)
$I_{DD4R}$	1443	1623	2298	2658	1893	2118	3198	3648	mA	1)3)4)
$I_{DD4W}$	1533	1713	2478	2838	1983	2208	3378	3828	mA	1)4)
$I_{DD5}$	1803	2208	3018	3828	2253	2703	3918	4818	mA	1)4)
$I_{DD6}$	390	399	403	421	403	421	430	466	mA	2)4)
$I_{DD7}$	2128	2613	3668	4638	2578	3108	4568	5628	mA	1)3)4)

- 1) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $n * I_{DD} \times [\text{component}] + n * I_{DD3N} [\text{component}]$  for two bank modules (n: number of components per module bank)
- 2) The module  $I_{DD}$  values are calculated from the component  $I_{DD}$  datasheet values are:  
 $n * I_{DD} \times [\text{component}]$  for single bank modules (n: number of components per module bank)  
 $2 * n * I_{DD} \times [\text{component}]$  for single two bank modules (n: number of components per module bank)
- 3) DQ I/O ( $I_{DDQ}$ ) currents are not included into calculations: module  $I_{DD}$  values will be measured differently depending on load conditions
- 4) Module  $I_{DD}$  is calculated on the basis of component  $I_{DD}$  and includes Register and PLL
- 5) Test condition for maximum values:  $V_{DD} = 2.7 \text{ V}$ ,  $T_A = 10 \text{ °C}$

### 3.2 AC Characteristics

**Table 12 AC Timing - Absolute Specifications -5/-6/-7**

Parameter	Symbol	-5		-6		-7		Unit	Note/ Test Condition <sup>1)</sup>
		DDR400B		DDR333		DDR266A			
		Min.	Max.	Min.	Max.	Min.	Max.		
DQ output access time from CK/ $\overline{\text{CK}}$	$t_{AC}$	-0.7	+0.7	-0.7	+0.7	-0.75	+0.75	ns	2)3)4)5)
DQS output access time from CK/ $\overline{\text{CK}}$	$t_{DQSCK}$	-0.6	+0.6	-0.6	+0.6	-0.75	+0.75	ns	2)3)4)5)
CK high-level width	$t_{CH}$	0.45	0.55	0.45	0.55	0.45	0.55	$t_{CK}$	2)3)4)5)
CK low-level width	$t_{CL}$	0.45	0.55	0.45	0.55	0.45	0.55	$t_{CK}$	2)3)4)5)
Clock Half Period	$t_{HP}$	min. ( $t_{CL}$ , $t_{CH}$ )		min. ( $t_{CL}$ , $t_{CH}$ )		min. ( $t_{CL}$ , $t_{CH}$ )		ns	2)3)4)5)
Clock cycle time	$t_{CK}$	5	8	—	—	—	—	ns	CL = 3.0 <sup>2)3)4)5)</sup>
		6	12	6	12	7.5	12	ns	CL = 2.5 <sup>2)3)4)5)</sup>
		7.5	12	7.5	12	7.5	12	ns	CL = 2.0 <sup>2)3)4)5)</sup>
DQ and DM input hold time	$t_{DH}$	0.4	—	0.45	—	0.5	—	ns	2)3)4)5)
DQ and DM input setup time	$t_{DS}$	0.4	—	0.45	—	0.5	—	ns	2)3)4)5)
Control and Addr. input pulse width (each input)	$t_{IPW}$	2.2	—	2.2	—	2.2	—	ns	2)3)4)5)6)
DQ and DM input pulse width (each input)	$t_{DIPW}$	1.75	—	1.75	—	1.75	—	ns	2)3)4)5)6)
Data-out high-impedance time from CK/ $\overline{\text{CK}}$	$t_{HZ}$	—	+0.7	—	+0.7	—	+0.75	ns	2)3)4)5)7)
Data-out low-impedance time from CK/ $\overline{\text{CK}}$	$t_{LZ}$	-0.7	+0.7	-0.7	+0.7	-0.75	+0.75	ns	2)3)4)5)7)
Write command to 1 <sup>st</sup> DQS latching transition	$t_{DQSS}$	0.72	1.25	0.75	1.25	0.75	1.25	$t_{CK}$	2)3)4)5)
DQS-DQ skew (DQS and associated DQ signals)	$t_{DQSQ}$	—	+0.4	—	+0.4	—	+0.5	ns	TFBGA <sup>2)3)4)5)</sup>
Data hold skew factor	$t_{QHS}$	—	+0.5	—	+0.55	—	+0.75	ns	TFBGA <sup>2)3)4)5)</sup>
DQ/DQS output hold time	$t_{QH}$	$t_{HP} - t_{QHS}$	—	$t_{HP} - t_{QHS}$	—	$t_{HP} - t_{QHS}$	—	ns	2)3)4)5)
DQS input low (high) pulse width (write cycle)	$t_{DQSL,H}$	0.35	—	0.35	—	0.35	—	$t_{CK}$	2)3)4)5)
DQS falling edge to CK setup time (write cycle)	$t_{DSS}$	0.2	—	0.2	—	0.2	—	$t_{CK}$	2)3)4)5)
DQS falling edge hold time from CK (write cycle)	$t_{DSH}$	0.2	—	0.2	—	0.2	—	$t_{CK}$	2)3)4)5)
Mode register set command cycle time	$t_{MRD}$	2	—	2	—	2	—	$t_{CK}$	2)3)4)5)
Write preamble setup time	$t_{WPRES}$	0	—	0	—	0	—	ns	2)3)4)5)8)
Write postamble	$t_{WPST}$	0.4	0.6	0.4	0.6	0.4	0.6	$t_{CK}$	2)3)4)5)9)
Write preamble	$t_{WPRE}$	0.25	—	0.25	—	0.25	—	$t_{CK}$	2)3)4)5)

**Table 12 AC Timing - Absolute Specifications –5/–6/–7 (cont'd)**

Parameter	Symbol	–5		–6		–7		Unit	Note/ Test Condition <sup>1)</sup>
		DDR400B		DDR333		DDR266A			
		Min.	Max.	Min.	Max.	Min.	Max.		
Address and control input setup time	$t_{IS}$	0.6	—	0.75	—	0.9	—	ns	fast slew rate 3)4)5)6)10)
		0.7	—	0.8	—	1.0	—	ns	slow slew rate 3)4)5)6)10)
Address and control input hold time	$t_{IH}$	0.6	—	0.75	—	0.9	—	ns	fast slew rate 3)4)5)6)10)
		0.7	—	0.8	—	1.0	—	ns	slow slew rate 3)4)5)6)10)
Read preamble	$t_{RPRE}$	0.9	1.1	0.9	1.1	0.90	1.1	$t_{CK}$	2)3)4)5)
Read postamble	$t_{RPST}$	0.4	0.6	0.4	0.6	0.4	0.6	$t_{CK}$	2)3)4)5)
Active to Precharge command	$t_{RAS}$	40	70E+3	42	70E+3	45	70E+3	ns	2)3)4)5)
Active to Active/Auto-refresh command period	$t_{RC}$	55	—	60	—	65	—	ns	2)3)4)5)
Auto-refresh to Active/Auto-refresh command period	$t_{RFC}$	65	—	72	—	75	—	ns	2)3)4)5)
Active to Read or Write delay	$t_{RCD}$	15	—	18	—	20	—	ns	2)3)4)5)
Precharge command period	$t_{RP}$	15	—	18	—	20	—	ns	2)3)4)5)
Active to Autoprecharge delay	$t_{RAP}$	$t_{RCD}$ or $t_{RASmin}$	—	$t_{RCD}$ or $t_{RASmin}$	—	$t_{RCD}$ or $t_{RASmin}$	—	ns	2)3)4)5)
Active bank A to Active bank B command	$t_{RRD}$	10	—	12	—	15	—	ns	2)3)4)5)
Write recovery time	$t_{WR}$	15	—	15	—	15	—	ns	2)3)4)5)
Auto precharge write recovery + precharge time	$t_{DAL}$	—	—	—	—	—	—	$t_{CK}$	2)3)4)5)11)
Internal write to read command delay	$t_{WTR}$	2	—	1	—	1	—	$t_{CK}$	2)3)4)5)
Exit self-refresh to non-read command	$t_{XSNR}$	75	—	75	—	75	—	ns	2)3)4)5)
Exit self-refresh to read command	$t_{XSRD}$	200	—	200	—	200	—	$t_{CK}$	2)3)4)5)
Average Periodic Refresh Interval	$t_{REFI}$	—	7.8	—	7.8	—	7.8	$\mu$ s	2)3)4)5)12)

1)  $0\text{ }^{\circ}\text{C} \leq T_A \leq 70\text{ }^{\circ}\text{C}$ ;  $V_{DDQ} = 2.5\text{ V} \pm 0.2\text{ V}$ ,  $V_{DD} = +2.5\text{ V} \pm 0.2\text{ V}$  (DDR333);  $V_{DDQ} = 2.6\text{ V} \pm 0.1\text{ V}$ ,  $V_{DD} = +2.6\text{ V} \pm 0.1\text{ V}$  (DDR400)

2) Input slew rate  $\geq 1\text{ V/ns}$  for DDR400, DDR333

3) The CK/ $\overline{\text{CK}}$  input reference level (for timing reference to CK/ $\overline{\text{CK}}$ ) is the point at which CK and  $\overline{\text{CK}}$  cross: the input reference level for signals other than CK/ $\overline{\text{CK}}$ , is  $V_{REF}$ . CK/ $\overline{\text{CK}}$  slew rate are  $\geq 1.0\text{ V/ns}$ .

4) Inputs are not recognized as valid until  $V_{REF}$  stabilizes.

5) The Output timing reference level, as measured at the timing reference point indicated in AC Characteristics (note 3) is  $V_{TT}$ .

6) These parameters guarantee device timing, but they are not necessarily tested on each device.

7)  $t_{HZ}$  and  $t_{LZ}$  transitions occur in the same access time windows as valid data transitions. These parameters are not referred to a specific voltage level, but specify when the device is no longer driving (HZ), or begins driving (LZ).



**Electrical Characteristics**

- 8) The specific requirement is that DQS be valid (HIGH, LOW, or some point on a valid transition) on or before this CK edge. A valid transition is defined as monotonic and meeting the input slew rate specifications of the device. When no writes were previously in progress on the bus, DQS will be transitioning from Hi-Z to logic LOW. If a previous write was in progress, DQS could be HIGH, LOW, or transitioning from HIGH to LOW at this time, depending on  $t_{DQSS}$ .
- 9) The maximum limit for this parameter is not a device limit. The device operates with a greater value for this parameter, but system performance (bus turnaround) degrades accordingly.
- 10) Fast slew rate  $\geq 1.0$  V/ns, slow slew rate  $\geq 0.5$  V/ns and  $< 1$  V/ns for command/address and CK &  $\overline{CK}$  slew rate  $> 1.0$  V/ns, measured between  $V_{OH(ac)}$  and  $V_{OL(ac)}$ .
- 11) For each of the terms, if not already an integer, round to the next highest integer.  $t_{CK}$  is equal to the actual system clock cycle time.
- 12) A maximum of eight Autorefresh commands can be posted to any given DDR SDRAM device.

## 4 SPD Contents

**Table 13** SPD Codes for HYS72D128320GBR–5, HYS72D64300GBR–5 and HYS72D32300GBR–5

Product Type & Organization	HYS72D128320GBR–5–B	HYS72D64300GBR–5–B	HYS72D64320GBR–5–B	HYS72D32300GBR–5–B	
	1 GByte	512 MB	512 MB	256 MB	
	×72	×72	×72	×72	
	2 Ranks	1 Rank	2 Ranks	1 Rank	
	Label Code	PC3200R–30331	PC3200R–30330	PC3200R–30330	PC3200R–30330
Jedec SPD Revision	Rev 1.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX
0	Programmed SPD Bytes in E2PROM	80	80	80	80
1	Total number of Bytes in E2PROM	08	08	08	08
2	Memory Type (DDR = 07h)	07	07	07	07
3	Number of Row Addresses	0D	0D	0D	0D
4	Number of Column Addresses	0B	0B	0A	0A
5	Number of DIMM Ranks	02	01	02	01
6	Data Width (LSB)	48	48	48	48
7	Data Width (MSB)	00	00	00	00
8	Interface Voltage Levels	04	04	04	04
9	tCK @ CLmax (Byte 18) [ns]	50	50	50	50
10	tAC SDRAM @ CLmax (Byte 18) [ns]	50	50	50	50
11	Error Correction Support	02	02	02	02
12	Refresh Rate	82	82	82	82
13	Primary SDRAM Width	04	04	08	08
14	Error Checking SDRAM Width	04	04	08	08
15	tCCD [cycles]	01	01	01	01

**Table 13 SPD Codes for HYS72D128320GBR-5, HYS72D643[00/20]GBR-5 and HYS72D32300GBR-5**

	Product Type & Organization	HYS72D128320GBR-5-B	HYS72D64300GBR-5-B	HYS72D64320GBR-5-B	HYS72D32300GBR-5-B
		1 GByte	512 MB	512 MB	256 MB
		×72	×72	×72	×72
		2 Ranks	1 Rank	2 Ranks	1 Rank
		Label Code	PC3200R-30331	PC3200R-30330	PC3200R-30330
	Jedec SPD Revision	Rev 1.0	Rev 0.0	Rev 0.0	Rev 0.0
Byte#	Description	HEX	HEX	HEX	HEX
16	Burst Length Supported	0E	0E	0E	0E
17	Number of Banks on SDRAM Device	04	04	04	04
18	CAS Latency	1C	1C	1C	1C
19	CS Latency	01	01	01	01
20	Write Latency	02	02	02	02
21	DIMM Attributes	26	26	26	26
22	Component Attributes	C0	C1	C1	C1
23	tCK @ CLmax -0.5 (Byte 18) [ns]	60	60	60	60
24	tAC SDRAM @ CLmax -0.5 [ns]	50	50	50	50
25	tCK @ CLmax -1 (Byte 18) [ns]	75	75	75	75
26	tAC SDRAM @ CLmax -1 [ns]	50	50	50	50
27	tRPmin [ns]	3C	3C	3C	3C
28	tRRDmin [ns]	28	28	28	28
29	tRCDmin [ns]	3C	3C	3C	3C
30	tRASmin [ns]	28	28	28	28
31	Module Density per Rank	80	80	40	40
32	tAS, tCS [ns]	60	60	60	60
33	tAH, TCH [ns]	60	60	60	60
34	tDS [ns]	40	40	40	40
35	tDH [ns]	40	40	40	40
36 - 40	not used	00	00	00	00
41	tRCmin [ns]	37	37	37	37

**Table 13** SPD Codes for HYS72D128320GBR-5, HYS72D64300GBR-5 and HYS72D32300GBR-5

	Product Type & Organization	HYS72D128320GBR-5-B	HYS72D64300GBR-5-B	HYS72D64320GBR-5-B	HYS72D32300GBR-5-B
		1 GByte	512 MB	512 MB	256 MB
		×72	×72	×72	×72
		2 Ranks	1 Rank	2 Ranks	1 Rank
		Label Code	PC3200R-30331	PC3200R-30330	PC3200R-30330
	Jedec SPD Revision	Rev 1.0	Rev 0.0	Rev 0.0	Rev 0.0
Byte#	Description	HEX	HEX	HEX	HEX
42	tRFCmin [ns]	41	41	41	41
43	tCKmax [ns]	28	28	28	28
44	tDQSQmax [ns]	28	28	28	28
45	tQHSmax [ns]	50	50	50	50
46	not used	00	00	00	00
47	DIMM PCB Height	01	00	00	00
48 - 61	not used	00	00	00	00
62	SPD Revision	10	00	00	00
63	Checksum of Byte 0-62	5F	4E	16	15
64	JEDEC ID Code of Infineon (1)	C1	C1	C1	C1
65	JEDEC ID Code of Infineon (2)	49	49	49	49
66	JEDEC ID Code of Infineon (3)	4E	4E	4E	4E
67	JEDEC ID Code of Infineon (4)	46	46	46	46
68	JEDEC ID Code of Infineon (5)	49	49	49	49
69	JEDEC ID Code of Infineon (6)	4E	4E	4E	4E
70	JEDEC ID Code of Infineon (7)	45	45	45	45
71	JEDEC ID Code of Infineon (8)	4F	4F	4F	4F
72	Module Manufacturer Location	xx	xx	xx	xx
73	Part Number, Char 1	37	37	37	37
74	Part Number, Char 2	32	32	32	32

**Table 13 SPD Codes for HYS72D128320GBR-5, HYS72D64300GBR-5 and HYS72D32300GBR-5**

	Product Type & Organization	HYS72D128320GBR-5-B	HYS72D64300GBR-5-B	HYS72D64320GBR-5-B	HYS72D32300GBR-5-B
		1 GByte	512 MB	512 MB	256 MB
		×72	×72	×72	×72
		2 Ranks	1 Rank	2 Ranks	1 Rank
		Label Code	PC3200R-30331	PC3200R-30330	PC3200R-30330
	Jedec SPD Revision	Rev 1.0	Rev 0.0	Rev 0.0	Rev 0.0
Byte#	Description	HEX	HEX	HEX	HEX
75	Part Number, Char 3	44	44	44	44
76	Part Number, Char 4	31	36	36	33
77	Part Number, Char 5	32	34	34	32
78	Part Number, Char 6	38	33	33	33
79	Part Number, Char 7	33	30	32	30
80	Part Number, Char 8	32	30	30	30
81	Part Number, Char 9	30	47	47	47
82	Part Number, Char 10	47	42	42	42
83	Part Number, Char 11	42	52	52	52
84	Part Number, Char 12	52	35	35	35
85	Part Number, Char 13	37	42	42	42
86	Part Number, Char 14	42	20	20	20
87	Part Number, Char 15	20	20	20	20
88	Part Number, Char 16	20	20	20	20
89	Part Number, Char 17	20	20	20	20
90	Part Number, Char 18	20	20	20	20
91	Module Revision Code	xx	xx	xx	xx
92	Test Program Revision Code	xx	xx	xx	xx
93	Module Manufacturing Date Year	xx	xx	xx	xx
94	Module Manufacturing Date Week	xx	xx	xx	xx
95	Module Serial Number (1)	xx	xx	xx	xx
96	Module Serial Number (2)	xx	xx	xx	xx
97	Module Serial Number (3)	xx	xx	xx	xx

**Table 13** SPD Codes for HYS72D128320GBR-5, HYS72D64300GBR-5 and HYS72D32300GBR-5

	Product Type & Organization	HYS72D128320GBR-5-B	HYS72D64300GBR-5-B	HYS72D64320GBR-5-B	HYS72D32300GBR-5-B
		1 GByte	512 MB	512 MB	256 MB
		×72	×72	×72	×72
		2 Ranks	1 Rank	2 Ranks	1 Rank
		Label Code	PC3200R-30331	PC3200R-30330	PC3200R-30330
Jedec SPD Revision	Rev 1.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX
98	Module Serial Number (4)	xx	xx	xx	xx
99 - 127	not used	00	00	00	00

**Table 14** SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
		Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
0	Programmed SPD Bytes in E2PROM	80	80	80	80	80
1	Total number of Bytes in E2PROM	08	08	08	08	08
2	Memory Type (DDR = 07h)	07	07	07	07	07

**Table 14 SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B**

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330	PC2700R-25330	
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
3	Number of Row Addresses	0D	0D	0D	0D	0D
4	Number of Column Addresses	0B	0B	0B	0A	0A
5	Number of DIMM Ranks	02	01	01	02	01
6	Data Width (LSB)	48	48	48	48	48
7	Data Width (MSB)	00	00	00	00	00
8	Interface Voltage Levels	04	04	04	04	04
9	tCK @ CLmax (Byte 18) [ns]	60	60	70	60	60
10	tAC SDRAM @ CLmax (Byte 18) [ns]	70	70	75	70	70
11	Error Correction Support	02	02	02	02	02
12	Refresh Rate	82	82	82	82	82
13	Primary SDRAM Width	04	04	04	08	08
14	Error Checking SDRAM Width	04	04	04	08	08
15	tCCD [cycles]	01	01	01	01	01
16	Burst Length Supported	0E	0E	0E	0E	0E
17	Number of Banks on SDRAM Device	04	04	04	04	04

**Table 14 SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B**

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330	PC2700R-25330	
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
18	CAS Latency	0C	0C	0C	0C	0C
19	CS Latency	01	01	01	01	01
20	Write Latency	02	02	02	02	02
21	DIMM Attributes	26	26	26	26	26
22	Component Attributes	C0	C0	C0	C0	C0
23	tCK @ CLmax - 0.5 (Byte 18) [ns]	75	75	75	75	75
24	tAC SDRAM @ CLmax -0.5 [ns]	70	70	75	70	70
25	tCK @ CLmax -1 (Byte 18) [ns]	00	00	00	00	00
26	tAC SDRAM @ CLmax -1 [ns]	00	00	00	00	00
27	tRPmin [ns]	48	48	50	48	48
28	tRRDmin [ns]	30	30	3C	30	30
29	tRCDmin [ns]	48	48	50	48	48
30	tRASmin [ns]	2A	2A	2D	2A	2A
31	Module Density per Rank	80	80	80	40	40
32	tAS, tCS [ns]	75	75	90	75	75
33	tAH, TCH [ns]	75	75	90	75	75
34	tDS [ns]	45	45	50	45	45
35	tDH [ns]	45	45	50	45	45
36 - 40	not used	00	00	00	00	00
41	tRCmin [ns]	3C	3C	41	3C	3C
42	tRFCmin [ns]	48	48	4B	48	48



**Table 14 SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B**

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
		Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
43	tCKmax [ns]	30	30	30	30	30
44	tDQSQmax [ns]	28	28	32	28	28
45	tQHSmax [ns]	50	50	75	50	50
46	not used	00	00	00	00	00
47	DIMM PCB Height	00	00	00	00	00
48 - 61	not used	00	00	00	00	00
62	SPD Revision	00	00	00	00	00
63	Checksum of Byte 0-62	48	47	03	0F	0E
64	JEDEC ID Code of Infineon (1)	C1	C1	C1	C1	C1
65	JEDEC ID Code of Infineon (2)	49	49	49	49	49
66	JEDEC ID Code of Infineon (3)	4E	4E	4E	4E	4E
67	JEDEC ID Code of Infineon (4)	46	46	46	46	46
68	JEDEC ID Code of Infineon (5)	49	49	49	49	49
69	JEDEC ID Code of Infineon (6)	4E	4E	4E	4E	4E
70	JEDEC ID Code of Infineon (7)	45	45	45	45	45
71	JEDEC ID Code of Infineon (8)	4F	4F	4F	4F	4F
72	Module Manufacturer Location	xx	xx	xx	xx	xx

**Table 14 SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B**

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330	PC2700R-25330	
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
73	Part Number, Char 1	37	37	37	37	37
74	Part Number, Char 2	32	32	32	32	32
75	Part Number, Char 3	44	44	44	44	44
76	Part Number, Char 4	31	36	36	36	33
77	Part Number, Char 5	32	34	34	34	32
78	Part Number, Char 6	38	33	33	33	33
79	Part Number, Char 7	33	30	30	32	30
80	Part Number, Char 8	32	30	30	30	30
81	Part Number, Char 9	30	47	47	47	47
82	Part Number, Char 10	47	42	42	42	42
83	Part Number, Char 11	42	52	52	52	52
84	Part Number, Char 12	52	36	37	36	36
85	Part Number, Char 13	36	42	42	42	42
86	Part Number, Char 14	42	20	20	20	20

**Table 14 SPD Codes for HYS72D128320GBR-6-B, HYS72D64300GBR-[6/7]-B, HYS72D64320GBR-6-B and HYS72D32300GBR-6-B**

	Product Type & Organization	HYS72D128320GBR-6-B	HYS72D64300GBR-6-B	HYS72D64300GBR-7-B	HYS72D64320GBR-6-B	HYS72D32300GBR-6-B
		1 GByte	512 MB	512 MB	512 MB	256 MB
		×72	×72	×72	×72	×72
		2 Ranks	1 Rank	1 Rank	2 Ranks	1 Rank
Label Code	PC2700R-25330	PC2700R-25330	PC2100R-20330	PC2700R-25330	PC2700R-25330	
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX	HEX	HEX
87	Part Number, Char 15	20	20	20	20	20
88	Part Number, Char 16	20	20	20	20	20
89	Part Number, Char 17	20	20	20	20	20
90	Part Number, Char 18	20	20	20	20	20
91	Module Revision Code	xx	xx	xx	xx	xx
92	Test Program Revision Code	xx	xx	xx	xx	xx
93	Module Manufacturing Date Year	xx	xx	xx	xx	xx
94	Module Manufacturing Date Week	xx	xx	xx	xx	xx
95	Module Serial Number (1)	xx	xx	xx	xx	xx
96	Module Serial Number (2)	xx	xx	xx	xx	xx
97	Module Serial Number (3)	xx	xx	xx	xx	xx
98	Module Serial Number (4)	xx	xx	xx	xx	xx
99 - 127	not used	00	00	00	00	00

**Table 15 SPD Codes for HYS72D[64/128]320GBR-7-B and HYS72D32300GBR-7-B**

	Product Type & Organization	HYS72D128320GBR-7-B	HYS72D64320GBR-7-B	HYS72D32300GBR-7-B
		1 GByte	512 MB	256 MB
		×72	×72	×72
		2 Ranks	2 Ranks	1 Rank
		Label Code	PC2100R-20330	PC2100R-20330
	Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0
Byte#	Description	HEX	HEX	HEX
0	Programmed SPD Bytes in E2PROM	80	80	80
1	Total number of Bytes in E2PROM	08	08	08
2	Memory Type (DDR = 07h)	07	07	07
3	Number of Row Addresses	0D	0D	0D
4	Number of Column Addresses	0B	0A	0A
5	Number of DIMM Ranks	02	02	01
6	Data Width (LSB)	48	48	48
7	Data Width (MSB)	00	00	00
8	Interface Voltage Levels	04	04	04
9	tCK @ CLmax (Byte 18) [ns]	70	70	70
10	tAC SDRAM @ CLmax (Byte 18) [ns]	75	75	75
11	Error Correction Support	02	02	02
12	Refresh Rate	82	82	82
13	Primary SDRAM Width	04	08	08
14	Error Checking SDRAM Width	04	08	08
15	tCCD [cycles]	01	01	01
16	Burst Length Supported	0E	0E	0E
17	Number of Banks on SDRAM Device	04	04	04
18	CAS Latency	0C	0C	0C
19	CS Latency	01	01	01
20	Write Latency	02	02	02
21	DIMM Attributes	26	26	26
22	Component Attributes	C0	C0	C0
23	tCK @ CLmax -0.5 (Byte 18) [ns]	75	75	75
24	tAC SDRAM @ CLmax -0.5 [ns]	75	75	75
25	tCK @ CLmax -1 (Byte 18) [ns]	00	00	00

**Table 15 SPD Codes for HYS72D[64/128]320GBR-7-B and HYS72D32300GBR-7-B**

	Product Type & Organization	HYS72D128320GBR-7-B	HYS72D64320GBR-7-B	HYS72D32300GBR-7-B
		1 GByte	512 MB	256 MB
		×72	×72	×72
		2 Ranks	2 Ranks	1 Rank
		Label Code	PC2100R-20330	PC2100R-20330
	Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0
Byte#	Description	HEX	HEX	HEX
26	tAC SDRAM @ CLmax -1 [ns]	00	00	00
27	tRPmin [ns]	50	50	50
28	tRRDmin [ns]	3C	3C	3C
29	tRCDmin [ns]	50	50	50
30	tRASmin [ns]	2D	2D	2D
31	Module Density per Rank	80	40	40
32	tAS, tCS [ns]	90	90	90
33	tAH, TCH [ns]	90	90	90
34	tDS [ns]	50	50	50
35	tDH [ns]	50	50	50
36 - 40	not used	00	00	00
41	tRCmin [ns]	41	41	41
42	tRFCmin [ns]	4B	4B	4B
43	tCKmax [ns]	30	30	30
44	tDQSQmax [ns]	32	32	32
45	tQHSmax [ns]	75	75	75
46	not used	00	00	00
47	DIMM PCB Height	00	00	00
48 - 61	not used	00	00	00
62	SPD Revision	00	00	00
63	Checksum of Byte 0-62	04	CB	CA
64	JEDEC ID Code of Infineon (1)	C1	C1	C1
65	JEDEC ID Code of Infineon (2)	49	49	49
66	JEDEC ID Code of Infineon (3)	4E	4E	4E
67	JEDEC ID Code of Infineon (4)	46	46	46
68	JEDEC ID Code of Infineon (5)	49	49	49
69	JEDEC ID Code of Infineon (6)	4E	4E	4E

**Table 15 SPD Codes for HYS72D[64/128]320GBR–7–B and HYS72D32300GBR–7–B**

	Product Type & Organization	HYS72D128320GBR–7–B	HYS72D64320GBR–7–B	HYS72D32300GBR–7–B
		1 GByte	512 MB	256 MB
		×72	×72	×72
		2 Ranks	2 Ranks	1 Rank
Label Code	PC2100R–20330	PC2100R–20330	PC2100R–20330	
Jedec SPD Revision	Rev 0.0	Rev 0.0	Rev 0.0	
Byte#	Description	HEX	HEX	HEX
70	JEDEC ID Code of Infineon (7)	45	45	45
71	JEDEC ID Code of Infineon (8)	4F	4F	4F
72	Module Manufacturer Location	xx	xx	xx
73	Part Number, Char 1	37	37	37
74	Part Number, Char 2	32	32	32
75	Part Number, Char 3	44	44	44
76	Part Number, Char 4	31	36	33
77	Part Number, Char 5	32	34	32
78	Part Number, Char 6	38	33	33
79	Part Number, Char 7	33	32	30
80	Part Number, Char 8	32	30	30
81	Part Number, Char 9	30	47	47
82	Part Number, Char 10	47	42	42
83	Part Number, Char 11	42	52	52
84	Part Number, Char 12	52	37	37
85	Part Number, Char 13	37	42	42
86	Part Number, Char 14	42	20	20
87	Part Number, Char 15	20	20	20
88	Part Number, Char 16	20	20	20
89	Part Number, Char 17	20	20	20
90	Part Number, Char 18	20	20	20
91	Module Revision Code	xx	xx	xx
92	Test Program Revision Code	xx	xx	xx
93	Module Manufacturing Date Year	xx	xx	xx
94	Module Manufacturing Date Week	xx	xx	xx
95	Module Serial Number (1)	xx	xx	xx
96	Module Serial Number (2)	xx	xx	xx

**Table 15 SPD Codes for HYS72D[64/128]320GBR-7-B and HYS72D32300GBR-7-B**

	Product Type & Organization	HYS72D128320GBR-7-B	HYS72D64320GBR-7-B	HYS72D32300GBR-7-B	
			<b>1 GByte</b>	<b>512 MB</b>	<b>256 MB</b>
			<b>×72</b>	<b>×72</b>	<b>×72</b>
			<b>2 Ranks</b>	<b>2 Ranks</b>	<b>1 Rank</b>
		<b>Label Code</b>	<b>PC2100R-20330</b>	<b>PC2100R-20330</b>	<b>PC2100R-20330</b>
	<b>Jedec SPD Revision</b>	<b>Rev 0.0</b>	<b>Rev 0.0</b>	<b>Rev 0.0</b>	
<b>Byte#</b>	<b>Description</b>	<b>HEX</b>	<b>HEX</b>	<b>HEX</b>	
97	Module Serial Number (3)	xx	xx	xx	
98	Module Serial Number (4)	xx	xx	xx	
99 - 127	not used	00	00	00	

## 5 Package Outlines

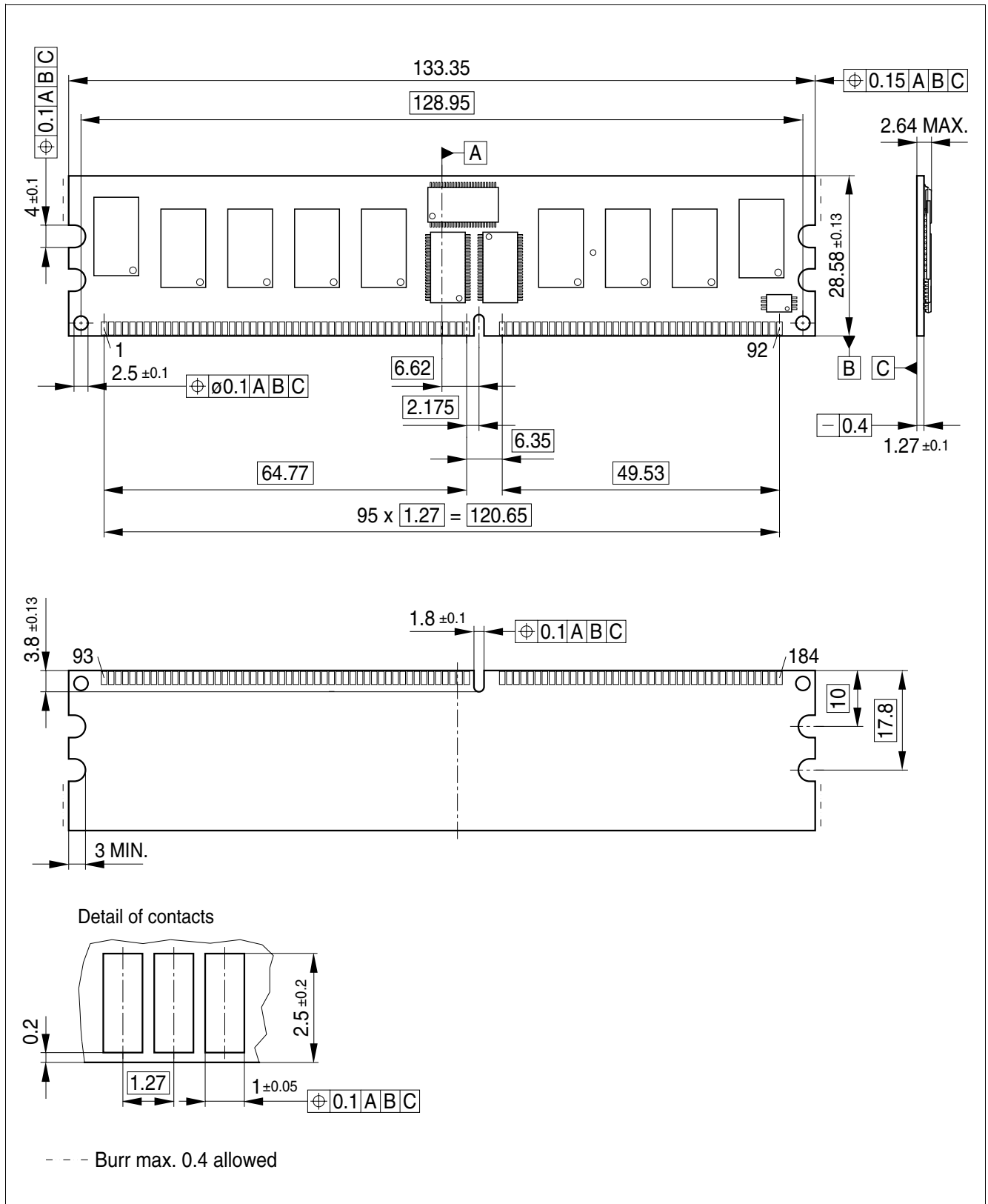


Figure 6 Package Outlines Raw Card A L-DIM 184-21



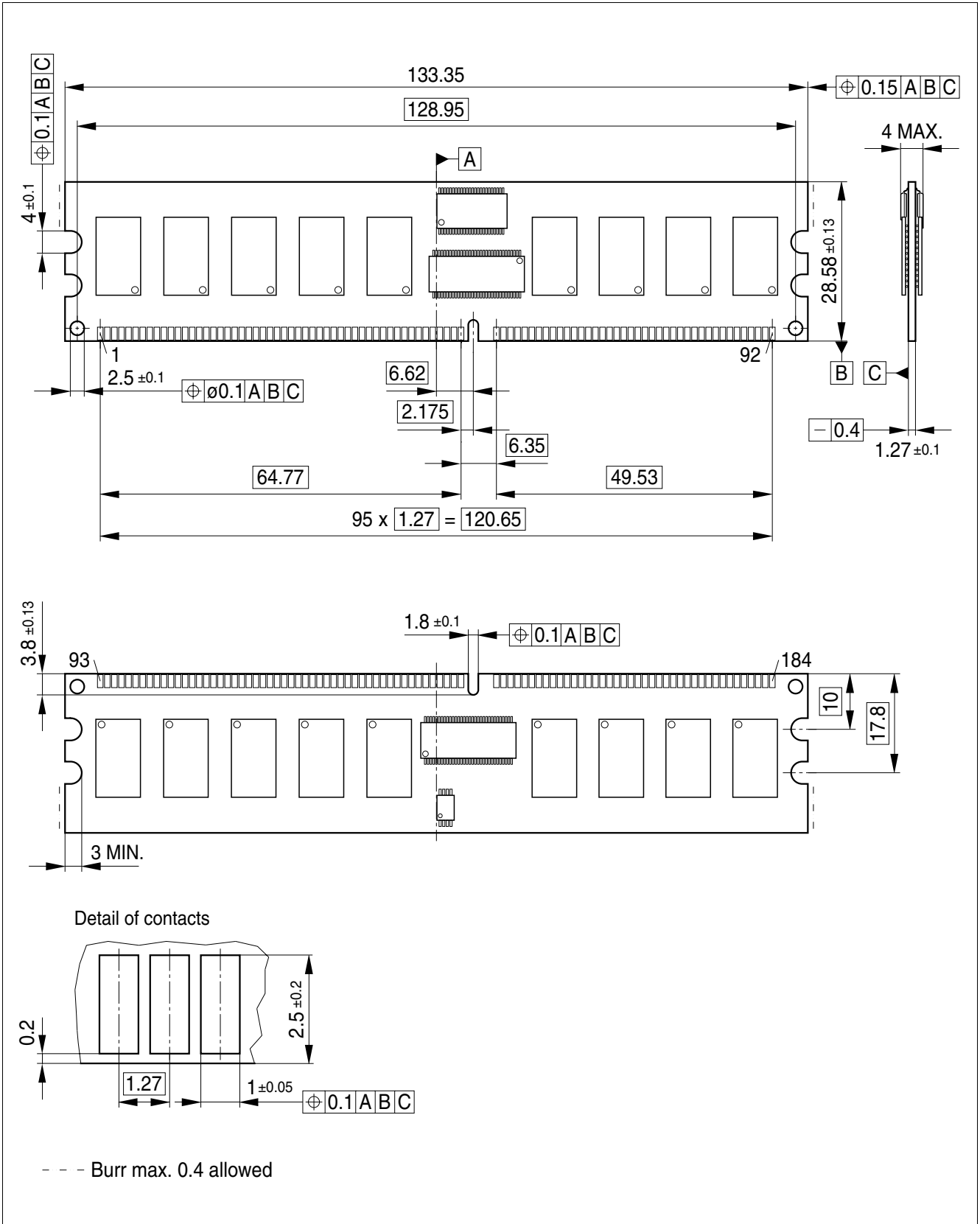


Figure 7 Package Outlines Raw Card B L-DIM 184-23

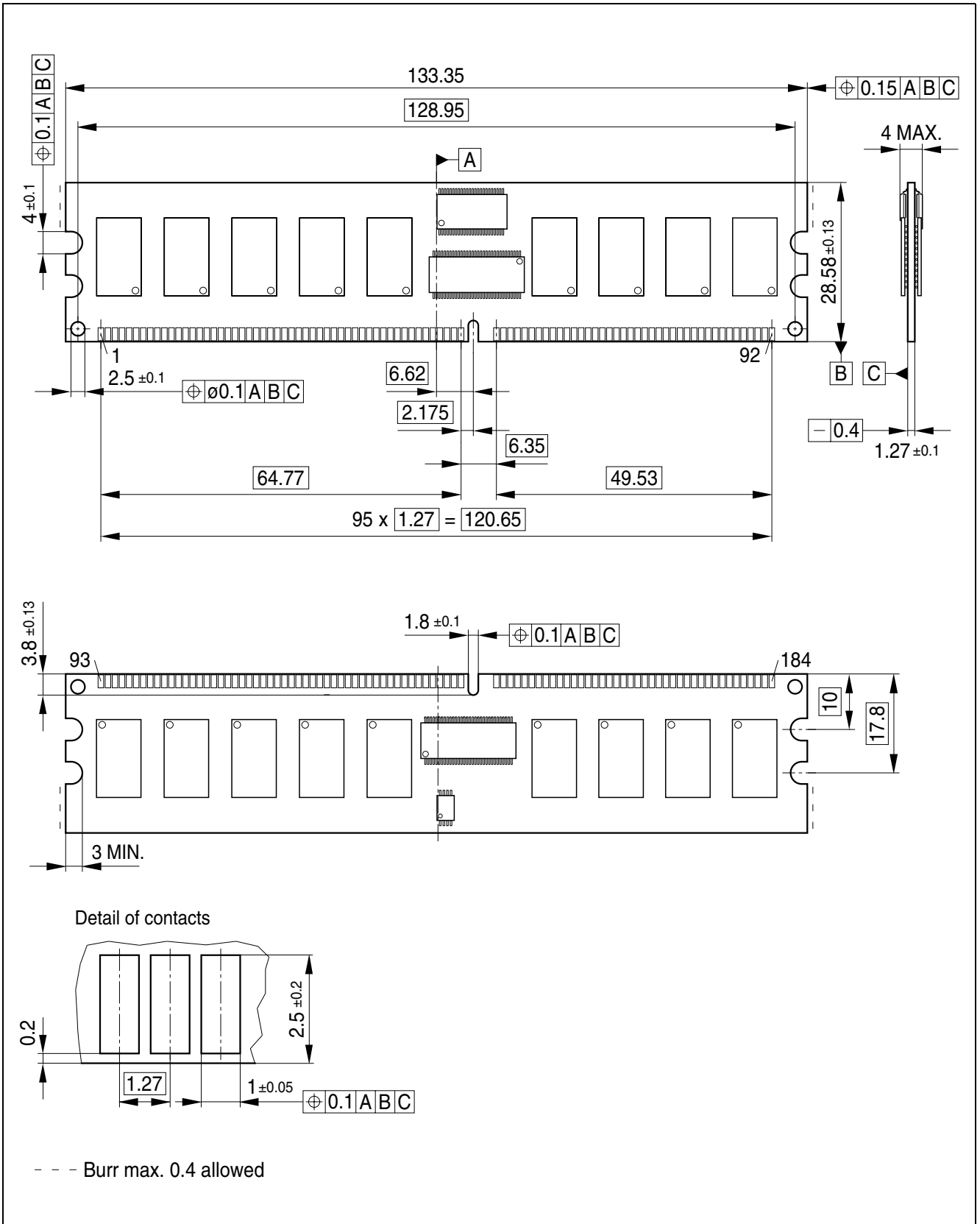


Figure 8 Package Outline Raw Card C L-DIM 184-22



## 6 Application Note

### Power Up and Power Management on DDR Registered DIMMs (according to JEDEC ballot JC-42.5 Item 1173)

184-pin Double Data Rate (DDR) Registered DIMMs include two new features to facilitate controlled power-up and to minimize power consumption during low power mode. One feature is externally controlled via a system-generated RESET signal; the second is based on module detection of the input clocks. These enhancements permit the modules to power up with SDRAM outputs in a High-Z state (eliminating risk of high current dissipations and/or dotted I/Os), and result in the powering-down of module support devices (registers and Phase-Locked Loop) when the memory is in Self-Refresh mode.

The new RESET pin controls power dissipation on the module's registers and ensures that CKE and other SDRAM inputs are maintained at a valid 'low' level during power-up and self refresh. When RESET is at a low level, all the register outputs are forced to a low level, and all differential register input receivers are powered down, resulting in very low register power consumption. The  $\overline{\text{RESET}}$  pin, located on DIMM tab #10, is driven from the system as an asynchronous signal according to the attached details. Using this function also permits the system and DIMM clocks to be stopped during memory Self Refresh operation, while ensuring that the SDRAMs stay in Self Refresh mode.

Table 16  $\overline{\text{RESET}}$  Truth Table

Register Inputs				Register Outputs
RESET	CK	CK	Data in (D)	Data out (Q)
H	Rising	Falling	H	H
H	Rising	Falling	L	L
H	L or H	L or H	X	Qo
H	High Z	High Z	X	Illegal input conditions
L	X or Hi-Z	X or Hi-Z	X or Hi-Z	L

X: Don't care, Hi-Z: High Impedance, Qo: Data latched at the previous of CK rising and  $\overline{\text{CK}}$  falling

As described in the table above, a low on the  $\overline{\text{RESET}}$  input ensures that the Clock Enable (CKE) signal(s) are maintained low at the SDRAM pins (CKE being one of the 'Q' signals at the register output). Holding CKE low maintains a high impedance state on the SDRAM DQ, DQS and DM outputs — where they will remain until activated by a valid 'read' cycle. CKE low also maintains SDRAMs in Self Refresh mode when applicable.

The DDR PLL devices automatically detect clock activity above 20MHz. When an input clock frequency of 20MHz or greater is detected, the PLL begins operation and initiates clock frequency lock (the minimum operating frequency at which all specifications will be met is 95MHz). If the clock input frequency drops below 20MHz (actual detect frequency will vary by vendor), the PLL VCO (Voltage Controlled Oscillator) is stopped, outputs are made High-Z, and the differential inputs are powered down — resulting in a total PLL current consumption of less than 1mA. Use of this low power PLL function makes the use of the PLL  $\overline{\text{RESET}}$  (or  $\overline{\text{G}}$  pin) unnecessary, and it is tied inactive on the DIMM.

This application note describes the required and optional system sequences associated with the DDR Registered DIMM 'RESET' function. It is important to note that all references to CKE refer to both CKE0 and CKE1 for a 2-bank DIMM. Because  $\overline{\text{RESET}}$  applies to all DIMM register devices, it is therefore not possible to uniquely control CKE to one physical DIMM bank through the use of the RESET pin.

### Power-Up Sequence with $\overline{\text{RESET}}$ — Required

1. The system sets  $\overline{\text{RESET}}$  at a valid low level.  
This is the preferred default state during power-up. This input condition forces all register outputs to a low state independent of the condition on the register inputs (data and clock), ensuring that CKE is at a stable low-level at the DDR SDRAMs.
2. The power supplies should be initialized according to the JEDEC-approved initialization sequence for DDR SDRAMs.
3. Stabilization of Clocks to the SDRAM  
The system must drive clocks to the application frequency (PLL operation is not assured until the input clock reaches 20 MHz). Stability of clocks at the SDRAMs will be affected by all applicable system clock devices, and time must be allotted to permit all clock devices to settle. Once a stable clock is received at the DIMM PLL, the required PLL stabilization time (assuming power to the DIMM is stable) is 100 microseconds. When a stable clock is present at the SDRAM input (driven from the PLL), the DDR SDRAM requires 200  $\mu\text{sec}$  prior to SDRAM operation.
4. The system applies valid logic levels to the data inputs of the register (address and controls at the DIMM connector).  
CKE must be maintained low and all other inputs should be driven to a known state. In general these commands can be determined by the system designer. One option is to apply an SDRAM 'NOP' command (with CKE low), as this is the first command defined by the JEDEC initialization sequence (ideally this would be a 'NOP Deselect' command). A second option is to apply low levels on all of the register inputs to be consistent with the state of the register outputs.
5. The system switches  $\overline{\text{RESET}}$  to a logic 'high' level.  
The SDRAM is now functional and prepared to receive commands. Since the  $\overline{\text{RESET}}$  signal is asynchronous, setting the  $\overline{\text{RESET}}$  timing in relation to a specific clock edge is not required (during this period, register inputs must remain stable).
6. The system must maintain stable register inputs until normal register operation is attained.  
The registers have an activation time that allows their clock receivers, data input receivers, and output drivers sufficient time to be turned on and become stable. During this time the system must maintain the valid logic levels described in step 5. It is also a functional requirement that the registers maintain a low state at the CKE outputs to guarantee that the DDR SDRAMs continue to receive a low level on CKE. Register activation time ( $t(\text{ACT})$ ), from asynchronous switching of  $\overline{\text{RESET}}$  from low to high until the registers are stable and ready to accept an input signal, is specified in the register and DIMM documentation.
7. The system can begin the JEDEC-defined DDR SDRAM power-up sequence (according to the JEDEC-approved initialization sequence).

### Self Refresh Entry ( $\overline{\text{RESET}}$ low, clocks powered off) — Optional

Self Refresh can be used to retain data in DDR SDRAM DIMMs even if the rest of the system is powered down and the clocks are off. This mode allows the DDR SDRAMs on the DIMM to retain data without external clocking. Self Refresh mode is an ideal time to utilize the  $\overline{\text{RESET}}$  pin, as this can reduce register power consumption ( $\overline{\text{RESET}}$  low deactivates register CK and CK, data input receivers, and data output drivers).

1. The system applies Self Refresh entry command.  
(CKE  $\rightarrow$  Low,  $\overline{\text{CS}}$   $\rightarrow$  Low,  $\overline{\text{RAS}}$   $\rightarrow$  Low,  $\overline{\text{CAS}}$   $\rightarrow$  Low,  $\overline{\text{WE}}$   $\rightarrow$  High)

*Note: Note: The commands reach the DDR SDRAM one clock later due to the additional register pipelining on a Registered DIMM. After this command is issued to the SDRAM, all of the address and control and clock input conditions to the SDRAM are Don't Cares— with the exception of CKE.*

2. The system sets  $\overline{\text{RESET}}$  at a valid low level.  
This input condition forces all register outputs to a low state, independent of the condition on the register inputs (data and clock), and ensures that CKE, and all other control and address signals, are a stable low-level at the DDR SDRAMs. Since the  $\overline{\text{RESET}}$  signal is asynchronous, setting the  $\overline{\text{RESET}}$  timing in relation to a specific clock edge is not required.
3. The system turns off clock inputs to the DIMM. (Optional)
  - a. In order to reduce DIMM PLL current, the clock inputs to the DIMM are turned off, resulting in High-Z clock

inputs to both the SDRAMs and the registers. This must be done after the  $\overline{\text{RESET}}$  deactivate time of the register ( $t(\text{INACT})$ ). The deactivate time defines the time in which the clocks and the control and address signals must maintain valid levels after  $\overline{\text{RESET}}$  low has been applied and is specified in the register and DIMM documentation.

b. The system may release DIMM address and control inputs to High-Z.

This can be done after the  $\overline{\text{RESET}}$  deactivate time of the register. The deactivate time defines the time in which the clocks and the control and the address signals must maintain valid levels after  $\overline{\text{RESET}}$  low has been applied. It is highly recommended that CKE continue to remain low during this operation.

4. The DIMM is in lowest power Self Refresh mode.

#### Self Refresh Exit ( $\overline{\text{RESET}}$ low, clocks powered off) — Optional

1. Stabilization of Clocks to the SDRAM.

The system must drive clocks to the application frequency (PLL operation is not assured until the input clock reaches ~20MHz). Stability of clocks at the SDRAMs will be affected by all applicable system clock devices, and time must be allotted to permit all clock devices to settle. Once a stable clock is received at the DIMM PLL, the required PLL stabilization time (assuming power to the DIMM is stable) is 100 microseconds.

2. The system applies valid logic levels to the data inputs of the register (address and controls at the DIMM connector).

CKE must be maintained low and all other inputs should be driven to a known state. In general these commands can be determined by the system designer. One option is to apply an SDRAM 'NOP' command (with CKE low), as this is the first command defined by the JEDEC Self Refresh Exit sequence (ideally this would be a 'NOP Deselect' command). A second option is to apply low levels on all of the register inputs, to be consistent with the state of the register outputs.

3. The system switches  $\overline{\text{RESET}}$  to a logic 'high' level.

The SDRAM is now functional and prepared to receive commands. Since the  $\overline{\text{RESET}}$  signal is asynchronous,  $\overline{\text{RESET}}$  timing relationship to a specific clock edge is not required (during this period, register inputs must remain stable).

4. The system must maintain stable register inputs until normal register operation is attained.

The registers have an activation time that allows the clock receivers, input receivers, and output drivers sufficient time to be turned on and become stable. During this time the system must maintain the valid logic levels described in Step 2. It is also a functional requirement that the registers maintain a low state at the CKE outputs to guarantee that the DDR SDRAMs continue to receive a low level on CKE. Register activation time ( $t(\text{ACT})$ ), from asynchronous switching of  $\overline{\text{RESET}}$  from low to high until the registers are stable and ready to accept an input signal, is specified in the register and DIMM documentation.

5. System can begin the JEDEC-defined DDR SDRAM Self Refresh Exit Procedure.

#### Self Refresh Entry ( $\overline{\text{RESET}}$ low, clocks running) — Optional

Although keeping the clocks running increases power consumption from the on-DIMM PLL during self refresh, this is an alternate operating mode for these DIMMs.

1. System enters Self Refresh entry command.  
(CKE → Low, CS → Low, RAS → Low, CAS → Low,  $\overline{\text{WE}}$  → High)

*Note: Note: The commands reach the DDR SDRAM one clock later due to the additional register pipelining on a Registered DIMM. After this command is issued to the SDRAM, all of the address and control and clock input conditions to the SDRAM are Don't Cares — with the exception of CKE.*

2. The system sets  $\overline{\text{RESET}}$  at a valid low level.

This input condition forces all register outputs to a low state, independent of the condition on the data and clock register inputs, and ensures that CKE is a stable low-level at the DDR SDRAMs.

3. The system may release DIMM address and control inputs to High-Z.

This can be done after the  $\overline{\text{RESET}}$  deactivate time of the register ( $t(\text{INACT})$ ). The deactivate time describes the time in which the clocks and the control and the address signals must maintain valid levels after  $\overline{\text{RESET}}$  low has been applied. It is highly recommended that CKE continue to remain low during the operation.

4. The DIMM is in a low power, Self Refresh mode.

#### Self Refresh Exit ( $\overline{\text{RESET}}$ low, clocks running) — Optional

1. The system applies valid logic levels to the data inputs of the register (address and controls at the DIMM connector). CKE must be maintained low and all other inputs should be driven to a known state. In general these commands can be determined by the system designer. One option is to apply an SDRAM 'NOP' command (with CKE low), as this is the first command defined by the Self Refresh Exit sequence (ideally this would be a 'NOP Deselect' command). A second option is to apply low levels on all of the register inputs to be consistent with the state of the register outputs.
2. The system switches  $\overline{\text{RESET}}$  to a logic 'high' level.  
The SDRAM is now functional and prepared to receive commands. Since the  $\overline{\text{RESET}}$  signal is asynchronous, it does not need to be tied to a particular clock edge (during this period, register inputs must continue to remain stable).
3. The system must maintain stable register inputs until normal register operation is attained.  
The registers have an activation time that allows the clock receivers, input receivers, and output drivers sufficient time to be turned on and become stable. During this time the system must maintain the valid logic levels described in Step 1. It is also a functional requirement that the registers maintain a low state at the CKE outputs in order to guarantee that the DDR SDRAMs continue to receive a low level on CKE. This activation time, from asynchronous switching of  $\overline{\text{RESET}}$  from low to high, until the registers are stable and ready to accept an input signal, is  $t(\text{ACT})$  as specified in the register and DIMM documentation.
4. The system can begin JEDEC defined DDR SDRAM Self Refresh Exit Procedure.

#### Self Refresh Entry/Exit ( $\overline{\text{RESET}}$ high, clocks running) — Optional

As this sequence does not involve the use of the  $\overline{\text{RESET}}$  function, the JEDEC standard SDRAM specification explains in detail the method for entering and exiting Self Refresh for this case.

#### Self Refresh Entry ( $\overline{\text{RESET}}$ high, clocks powered off) — Not Permissible

In order to maintain a valid low level on the register output, it is required that either the clocks be running and the system drive a low level on CKE, or the clocks are powered off and  $\overline{\text{RESET}}$  is asserted low according to the sequence defined in this application note. In the case where  $\overline{\text{RESET}}$  remains high and the clocks are powered off, the PLL drives a High-Z clock input into the register clock input. Without the low level on  $\overline{\text{RESET}}$  an unknown DIMM state will result.

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Published by Infineon Technologies AG